

Part Number: XZMG55W-2

3.2x1.6mm SMD CHIP LED LAMP

Features

 \bullet Ideal for indication light on hand held products

• Long life and robust package

• Variety of lens types and color choices available

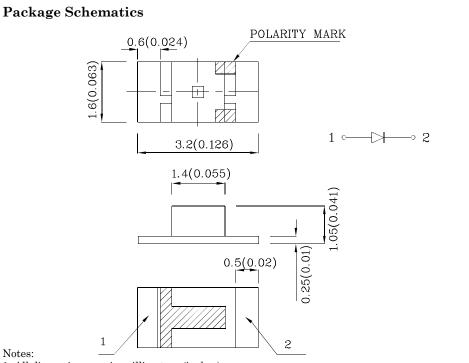
ullet Package : 2000 pcs / reel

• Moisture sensitivity level : level 3

• RoHS compliant







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		MG (GaP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	I_{F}	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	140	mA	
Power Dissipation	P_D	62.5	mW	
Operating Temperature	T_{A}	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85	ı	

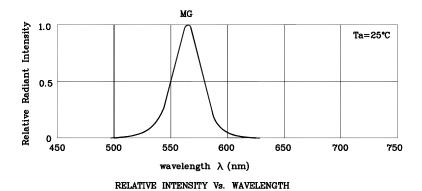
Operating Characteristics (T _A =25°C)		MG (GaP)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	2.2	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	V
Reverse Current (Max.) $(V_R=5V)$	${ m I}_{ m R}$	10	uA
Wavelength of Peak Emission (Typ.) (I _F =20mA)	λΡ	565	nm
Wavelength of Dominant Emission (Typ.) $(I_F=20\text{mA})$	λD	568	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$\triangle \lambda$	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

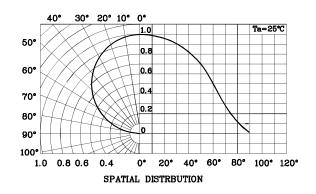
Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} \text{Luminous} \\ \text{Intensity} \\ \text{(I}_F=20\text{mA)} \\ \text{mcd} \end{array}$		Wavelength nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZMG55W-2	Green	GaP	Water Clear	8	14	565	120°

Apr 15,2011 XDSA1343 V7 Layout: Maggie L.

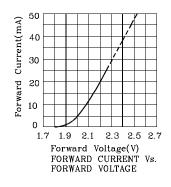


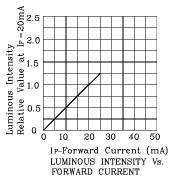


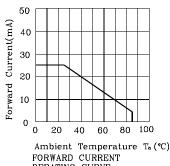


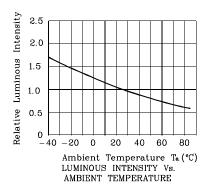


♦ MG



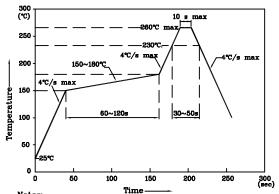






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

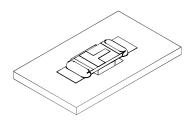


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

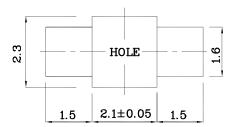




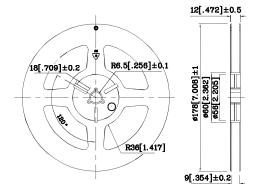
❖ The device has a single mounting surface. The device must be mounted according to the specifications.



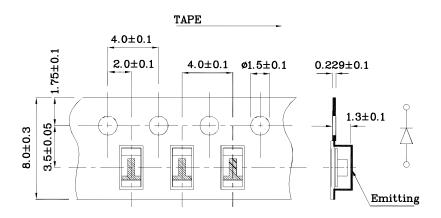
❖ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



❖ Reel Dimension



❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

Apr 15,2011

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PACKING & LABEL SPECIFICATIONS

